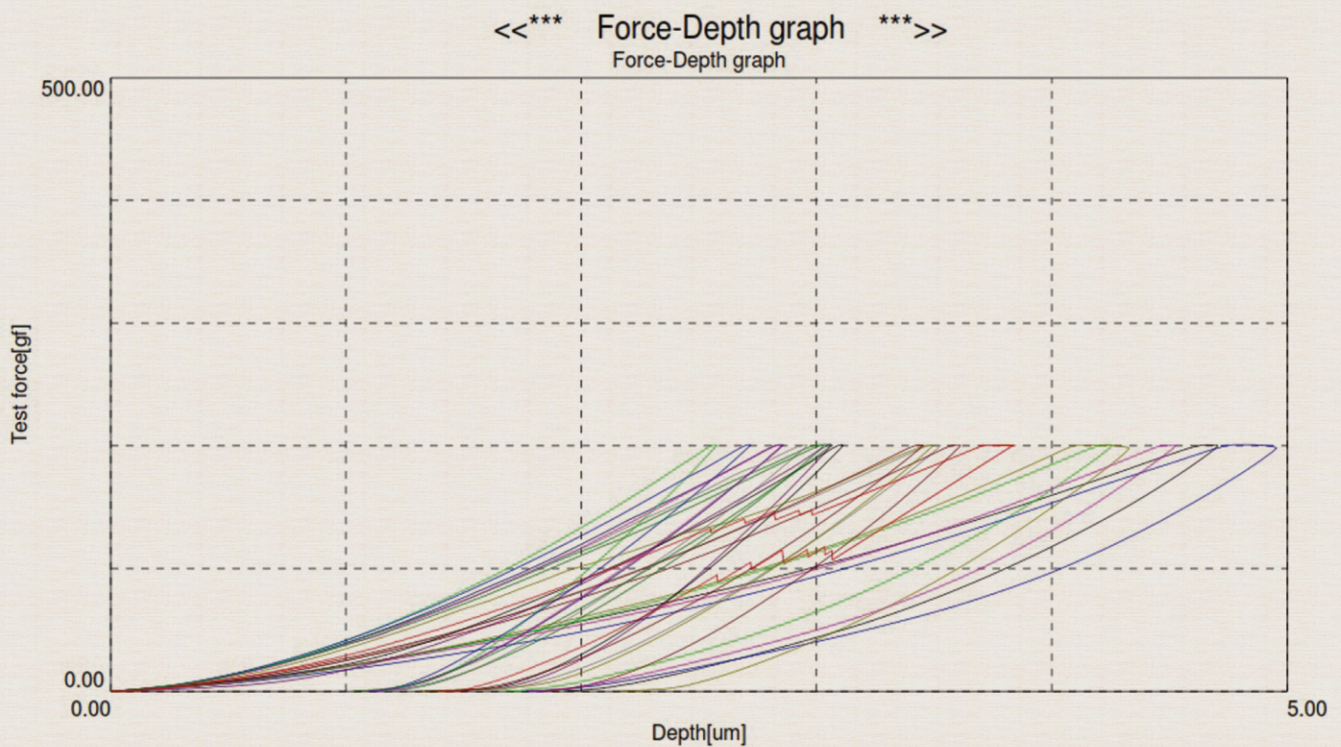


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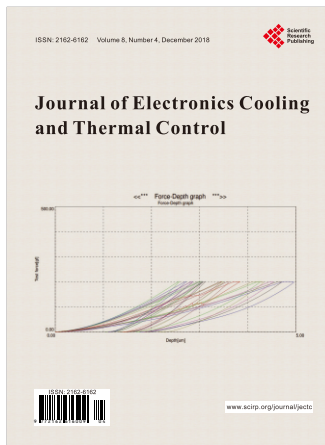
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- Natural convection heat transfer
- Phase changing heat transfer
- Phonon
- Radiation
- Spray cooling
- Temperature stability
- Thermal modeling of electronics systems and components

Technologies based on these transport processes such as

- Enhanced heat/mass transfer in precision-, micro-electronics, information technology
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